

Electronic Patent Application Fee Transmittal				
Application Number:		10595157		
Filing Date:		09-Mar-2006		
Title of Invention:		Method of Manufacturing Multi-Layer Circuit Board		
First Named Inventor/Applicant Name:		Toshiaki Takenaka		
Filer:		Andrew Lawson Dunlap/Lynn Donnelly		
Attorney Docket Number:		2006-0223A		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				940